



Process Change Notification

PCN Number: PCN-2019-119

PCN Notification Date: 11/22/2019

Final PCN

28L SSOP molding process migration from MGP (Multi Gang Pot) to Automold with mold compound material and part marking format change

Dear Customer,

We are pleased to announce the successful completion of the migration of the 28L SSOP molding process from the MGP mold conversion to an Automold process with a mold compound material change from Hitachi CEL 9220HF to Sumitomo G631LT along with a part marking format adjustment.

This document serves as the Final PCN notification for the migration of the 28L SSOP molding process from the MGP mold conversion to an Automold process with a mold compound material change from Hitachi CEL 9220HF to Sumitomo G631LT along with a part marking format adjustment.

The described change is effective as of the date of customer's agreement for this notification and delivery will commence immediately to ensure continuity of supply without disruption.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator
Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000



Process Change Notification

PCN Number: PCN-2019-119

PCN Notification Date: 11/22/2019

Products Affected:

The devices listed on subsequent pages are the complete list of affected devices. According to our records, one or more of these devices have been purchased by your organization within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:	28L SSOP molding process migration from MGP to Automold with mold compound material and part marking format change				
Customer Contact:	Local Field Sales Representative	Phone :	(512) 851-4000	Dept:	Customer Quality
Proposed 1st Ship Date:	Q1 2020	Estimated Sample Availability Date:		Q3 2019	
Change Type:					
	Assembly Site	X	Assembly Process	X	Assembly Materials
	Wafer Fab Site		Wafer Fab Process		Wafer Fab Materials
	Wafer Bump Site		Wafer Bump Process		Wafer Bump Material
	Test Site		Test Process		Design
	Electrical Specification		Mechanical Specification		Part Number
	Packing/Shipping/Labeling	X	Other		
Comments:	"Other" – Marking format				

PCN Details

Description of Change(s):

- 28L SSOP Molding Process**

From	To
MGP	Automold

MGP stands for Multi Gang Pot.

- Material Change**

From	To
MGP	Automold
Hitachi CEL 9220HF	Sumitomo G631LT


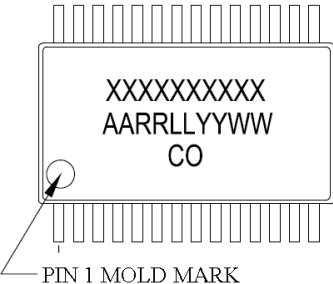
Note: Material Declarations or Product Content reports available upon request.

PCN Number: PCN-2019-119

PCN Notification Date: 11/22/2019

• **Marking Format: Consistent with Cirrus Logic Mark Format Standard**

Note: Cirrus Logic acquired Wolfson in August 2014

From	To	
<p>Wolfson Marking Format</p> 	<p>Cirrus Logic Marking Format</p> 	<p>Line 1: Part Number (10 characters maximum) Line 2: Package Mark (10 characters maximum) Line 3: Country of Origin (2 characters as shown on PO)</p> <p>AA = Assembly Site Code RR = Device Rev Code LL = Lot Sequence Code YY = Year of Manufacture WW = Work Week of Manufacture</p>

Reason for Change:

Cirrus Logics' 28L SSOP will migrate the existing molding process from MGP to Automold and aligned with OSE's standard molding process flow.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

No anticipated adverse impact to the Quality and/or Reliability of said product. However, the customer may have to adjust Pick-N-Place recognition system to adapt to the Cirrus Logic part marking format.

Anticipated Impact on Material Declaration:

- No Impact to the Material Declaration Material Declarations or Product Content reports are driven from production data and will be available following the production release.

Product Affected:

Cirrus Logic Part Number
WM8196SCDS/RV
WM8196SCDS/V
WM8510GEDS/RV
WM8510GEDS/V
WM8716SEDS/RV
WM8716SEDS/V
WM8778SEDS/RV
WM8778SEDS/V
WM8199SCDS/RV
WM8199SCDS/V
WM8213SCDS/RV
WM8213SCDS/V
WM8214SCDS/RV
WM8214SCDS/V
WM8740SEDS/RV
WM8740SEDS/V



Process Change Notification

PCN Number: PCN-2019-119

PCN Notification Date: 11/22/2019

WM8731SEDS/RV	
WM8731SEDS/V	
WM8569SEDS/RV	
WM8569SEDS/V	
WM8741GEDS/RV	
WM8741GEDS/V	
WM8742GEDS/RV	
WM8742GEDS/V	
WM8766GEDS/RV	
WM8766GEDS/V	
WM8805GEDS/RV	
WM8805GEDS/V	

Qualification Result

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Standard	Conditions	Sample Size (PASS/FAIL)
HTS (High Temperature Storage)	JESD22-A103	150 Deg.C, 1000 Hrs. No PC needed	3 Lots @ 77 pcs ea. Passed
PC (Precondition)	J-STD-020	Bake: 24Hr 125°C; MSL 3 192Hr 30°C / 60% RH Soak, (Reflow 260°C x3)	3 Lots @ 154 pcs ea. Passed
TC (Temperature Cycling)	JESD22-A104	-40°C to +125°C for 1000 cycles	3 Lots @ 77 pcs ea. Passed
BHAST (Biased Highly Accelerated Temperature and Humidity Stress Test)	JESD22-A110	110°C/85% RH, 264 hrs	3 Lots @ 77 pcs ea. Passed
Pkg Physical DIM			3 Lots @ 10 pcs ea. Passed
Notes: <ul style="list-style-type: none"> • Qualification tests “pass” on zero fails for each test. • The WM8741 component will serve as the primary qualification vehicle • The WM8569, WM8196 and WM8716 components passed HTSL, MSL, and TC. BHAST is QBS (Qualified By Similarity). • The remaining components are QBS (Qualified By Similarity). 			